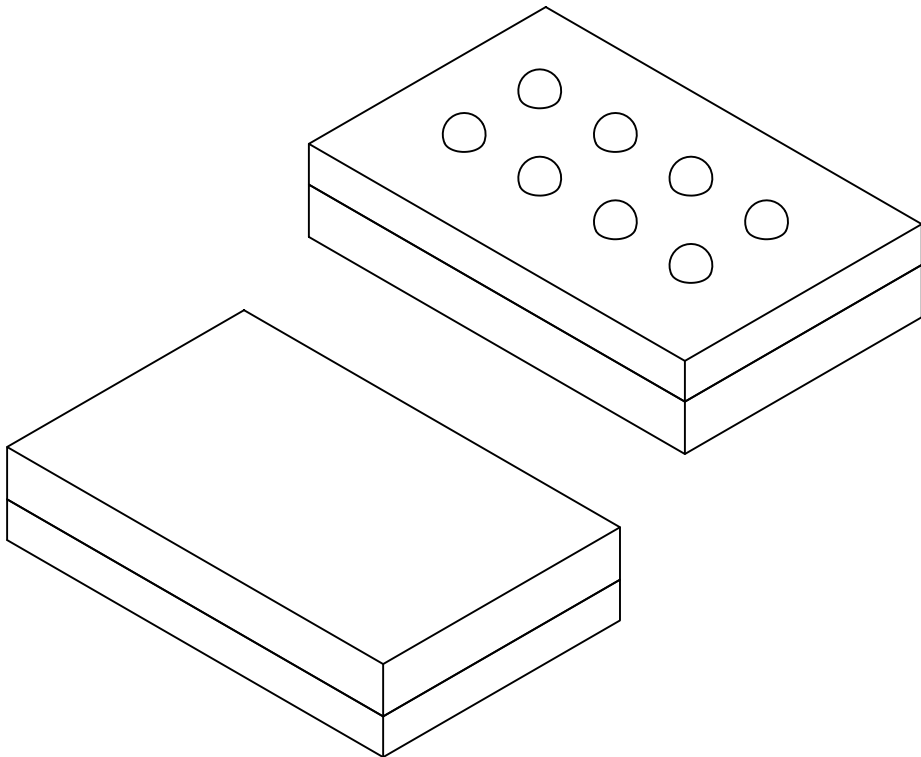


8-Ball Very-Thin Fine-Pitch Ball Grid Array (E9B) 2.35x3.73x1.0mm [VFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	8		
Pitch	e	0.75 BSC		
Overall Height	A	0.81	0.91	1.00
Ball Height	A1	0.15	0.20	0.25
Mold Thickness	A2	0.40	0.45	0.50
Substrate Thickness	A3	0.35 REF		
Overall Width	D	2.35 BSC		
Ball Array Width	D2	0.75 BSC		
Overall Length	E	3.73 BSC		
Ball Array Length	E2	2.25 BSC		
Ball Diameter	b	0.25	0.30	0.35

Notes:

- 1. The Pin 1 visual index feature may vary, but it must be located within the hatched area.
- 2. The package is saw singulated.
- 3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.